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Part Number: 5021184591

Status: Active

Description: 0.50mm (.020") Pitch Easy-On™ BackFlip™ FPC Connector, 0.90mm (.035") Height, Right Angle, SMT, Dual Contact Style, 45 Circuits, Lead-free

Documents:

Drawing (PDF)

Product Specification PS-502118-002 (PDF)

RoHS Certificate of Compliance (PDF)

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Not Reviewed
Halogen-Free Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
502118Series

General

Product Family	FFC/FPC Connectors
Series	502118
Product Name	BackFlip™, Easy-On™

Physical

Circuits (Loaded)	45
Color - Resin	Black, White
Contact Position	Dual
Durability (mating cycles max)	10
Entry Angle	90° Angle
Mated Height (in)	0.035 In
Mated Height (mm)	0.90 mm
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Number of Rows	1
Orientation	Right Angle
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.020 In
Pitch - Mating Interface (mm)	0.50 mm
Polarized to PCB	Yes
Stackable	No
Temperature Range - Operating	-40°C to +85°C
Termination Interface: Style	Surface Mount
Wire/Cable Type	FPC only

Electrical

Current - Maximum per Contact	0.5A
Voltage - Maximum	50V AC (RMS)/DC

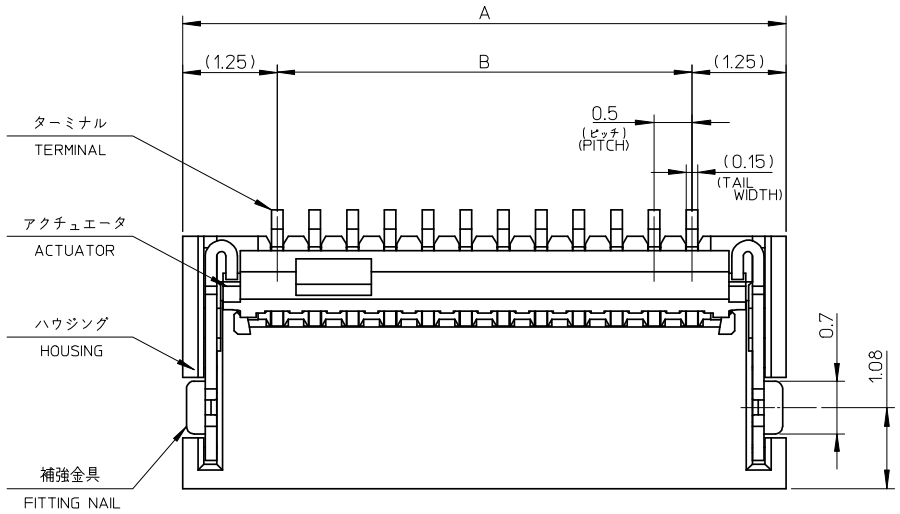
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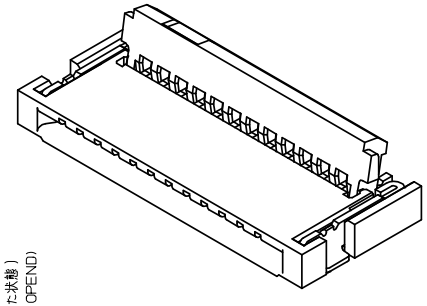
Reference - Drawing Numbers

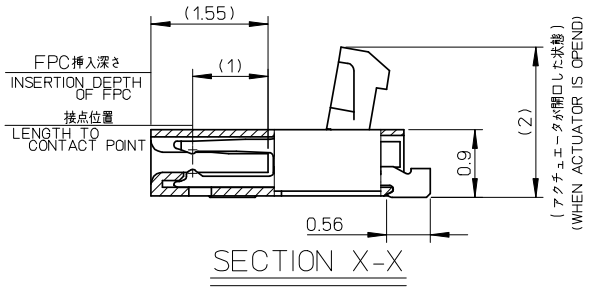
Product Specification	PS-502118-002
Sales Drawing	SD-502118-003, SD-502118-004

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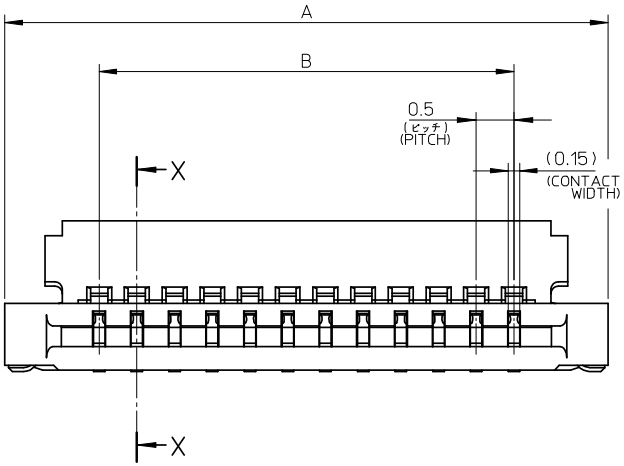
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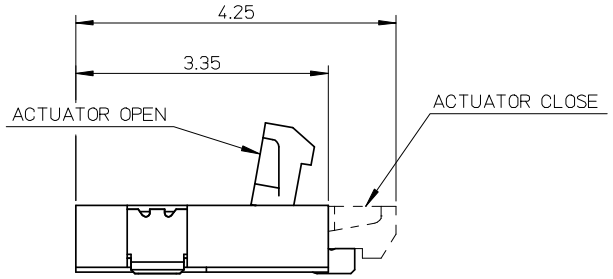






SECTION X-X





25.5	24.5	27	502118-5090	502118-5011	50
C	B	A	EMBOSSED PACKAGING ORDER NO.	MATERIAL NO.	CIRCUITS

RELEASED
EC NO: J2009-0131
DRWN:HONO01 2008/07/18
CH'KD:HSHIMOYAMA 2008/07/18
APPR:HHIRATA 2008/07/18
DESCRIPTION
0
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±1 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: //
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: HONO DATE: 2008/07/15
CHECKED BY: HSHIMOYAMA DATE: 2008/07/15
APPROVED BY: HHIRATA DATE: 2008/07/15
MATERIAL NO.: SEE CHART

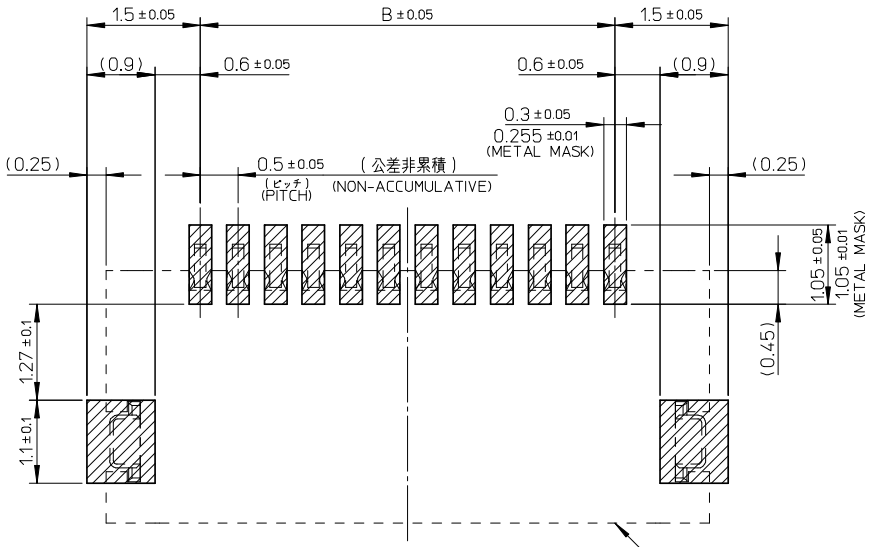
TITLE: 0.5 FPC CONN BACK FLIP H=0.9 UPR/BTM CONT

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DOCUMENT NO.: SD-502118-001
SHEET NO.: 1 OF 2

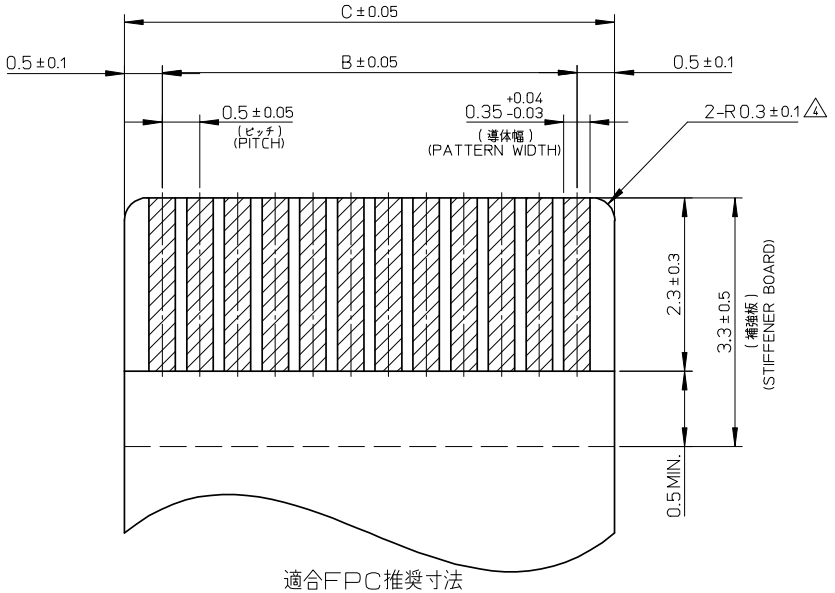
SIZE A3

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参考基板レイアウト
P.C.BOARD PATTERN DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)

コネクタ位置
CONNECTOR POSITION



適合FPC推奨寸法
APPLICABLE FPC RECOMMENDED DIMENSION
(仕上がり厚さ：0.20±0.03)
(THICKNESS : 0.20±0.03)

注 記 NOTE

推奨メタルマスク厚さ：0.12mm
RECOMMENDED METAL MASK THICKNESS:0.12mm

1. 使用材料 MATERIAL

ハウジング HOUSING	：ポリアミド樹脂，色：ベージュ	ガラス充填，UL94V-0 POLYAMIDE,COLOR:BEIGE GLASS FILLED,UL94V-0
アクチュエータ ACTUATOR	：ポリアミド樹脂，色：茶	ガラス充填， UL94V-0 POLYAMIDE,COLOR:BROWN GLASS FILLED,UL94V-0
ターミナル TERMINAL	：りん青銅(t=0.15)	PHOSPHOR BRONZE(t=0.15)
補強金具 FITTING NAIL	：りん青銅(t=0.15)	PHOSPHOR BRONZE(t=0.15)

2. めっき仕様 PLATING
   ターミナル
   TERMINAL
   ニッケル下地、部分金めっき(テールおよびコンタクト部)
   SEPARATED GOLD(TAIL AND CONTACT) OVER NICKEL PLATING.
   補強金具
   FITTING NAIL
   ニッケル下地錫めっき
   TIN OVER NICKEL PLATING.
3. 端子、補強金具の平坦度は0.1以下とする．
   COPLANALITY OF SOLDER TAIL AND FITTING NAIL : 0.1 MAX.

⚠4 R0.3はFPC導体部にかからないこと．
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

5. ELV及びRoHS適合品
   ELV AND RoHS COMPLIANT.
6. 基板実装前にアクチュエータを操作しないで下さい．
   必ず基板に実装し、FPCを挿入してから
   アクチュエータを操作して下さい．
   PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
   PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON THE SUBSTRATE,AND MATING FPC.

FPCについて
ABOUT FPC
抜き方向は、導体側から補強板を推奨します．
補強板材質は、ポリイミドを推奨します．
接着剤は熱硬化接着剤を推奨します．
なお、接着剤の接点部への付着は導通不良の原因となりますので染み出しの無いよう、お願いします．

RECOMMENDED PUNCHER DIRECTION :
FROM CONDUCTOR SIDE TO STIFFENER BORAD SIDE.
RECOMMENDED MATERIAL :
STIFFNER BOARD : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

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DESCRIPTION
REV 0

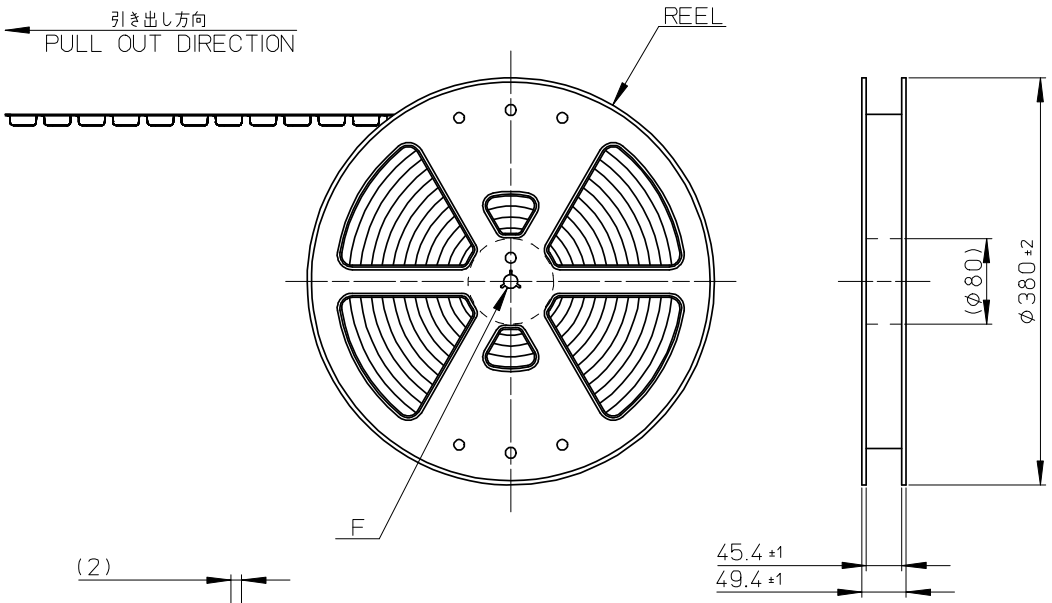
GENERAL TOLERANCES (UNLESS SPECIFIED)

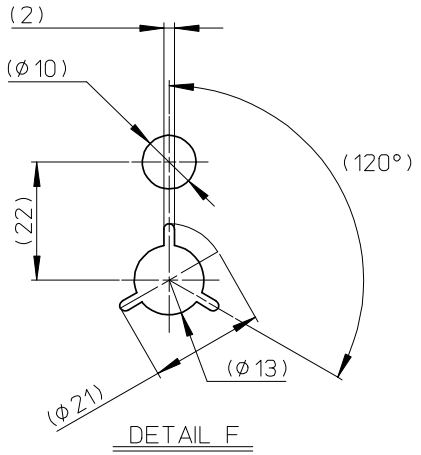
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±1 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	//
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	HONO
DATE	2008/07/15
CHECKED BY	HSHIMOYAMA
DATE	2008/07/15
APPROVED BY	HHIRATA
DATE	2008/07/15
MATERIAL NO.	SEE CHART
TITLE	0.5 FPC CONN BACK FLIP H=0.9 UPR/BTM CONT
	MOLEX INCORPORATED
DOCUMENT NO.	SD-502118-001
SHEET NO.	2 OF 2
SIZE	A3

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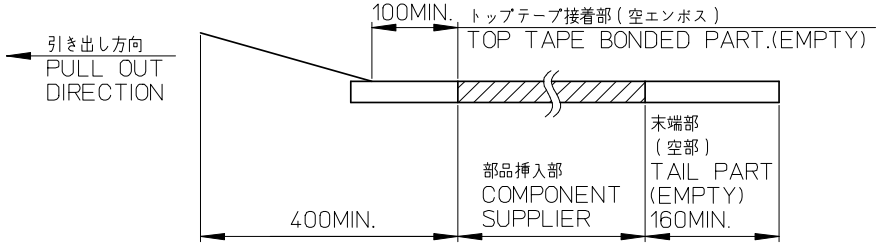




DETAIL F

NOTES

1.製品詳細寸法については製品単体図面を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
2.梱包数量：2500個／リール
NUMBER OF CONNECTORS 2500PCS/REEL
3.リードテープ長さ
LEAD TAPE LENGTH



4.材料
MATERIAL
キャリアテープ(CARRIRE TAPE)：ポリスチレン(POLYSTYRENE)
トップテープ(TOP TAPE)：PET, PE, PEF
リール(REEL)：ポリスチレン(PS) ＜リサイクル材を含む＞
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAILED>
5.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT.

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	CH'KD:HSHIMOYAMA	2008/07/18	
	APPR:HHIRATA	2008/07/18	
0			REV

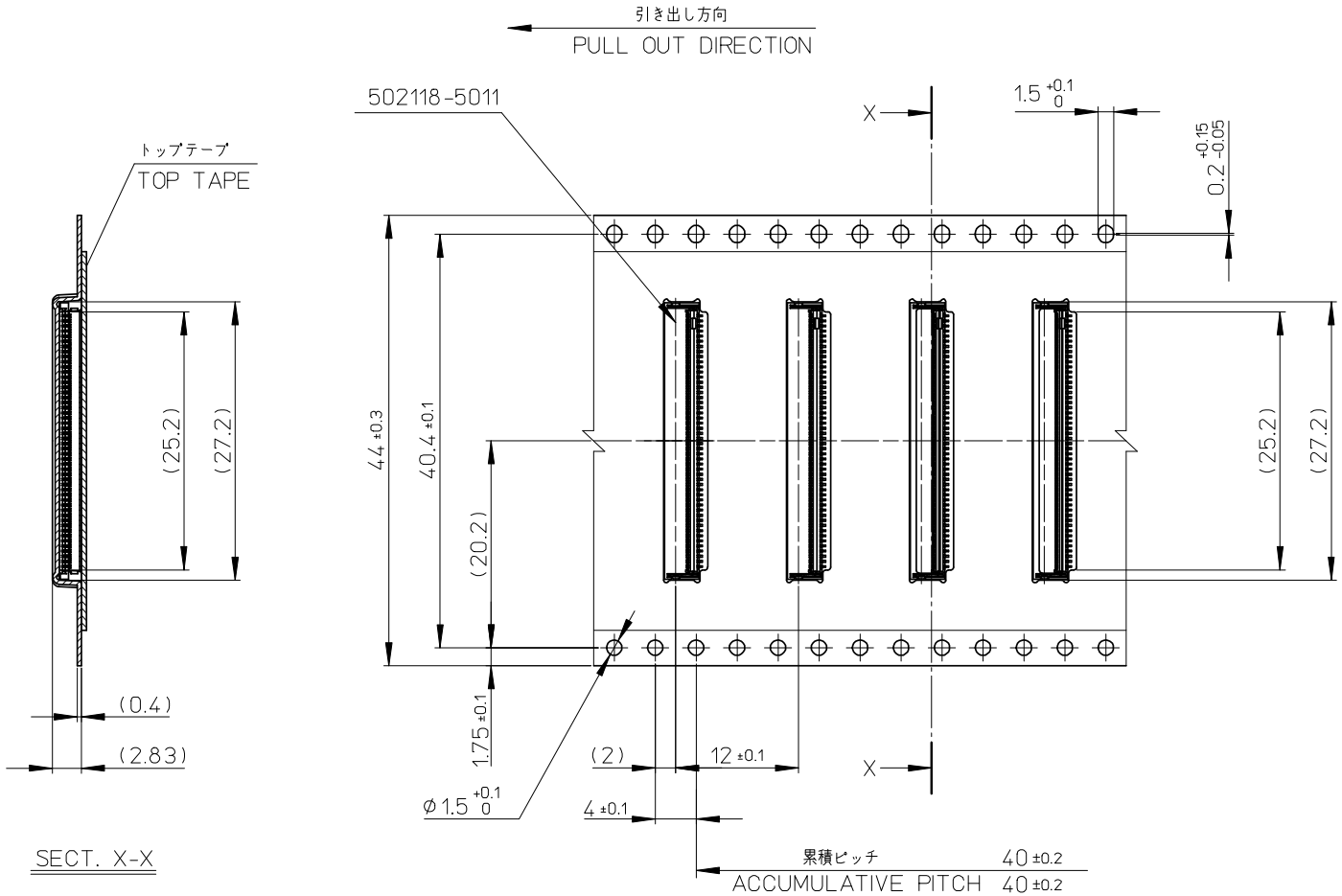
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DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	MM ONLY	SCALE	---
DESIGN UNITS	METRIC		THIRD ANGLE PROJECTION
DRAWN BY	HONO	DATE	2008/7/15
CHECKED BY	HSHIMOYAMA	DATE	2008/7/15
APPROVED BY	HHIRATA	DATE	2008/7/15
MATERIAL NO.	SEE CHART		
DOCUMENT NO.	SD-502118-002		SHEET NO. 1 OF 2
SIZE	A3		

TITLE
0.5 FPC CONN BACK FLIP
H=0.9 UPR/BTM CONT
EMBSTP PKG

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SECT. X-X

502118-5090	50
MATERIAL NO.	CIRCUITS

RELEASED
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DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
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DOCUMENT NO.: SD-502118-002

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